

**In the Claims:**

Please cancel claims 1-44 and 66-72.

1-44. (Canceled)

45. (Original) A planarizing pad for planarizing a microelectronic substrate, comprising:

a generally planar support portion; and

a plurality of texture elements disposed on the support portion, portions of the texture elements being spaced apart from each other and projecting from the support portion, each texture element having a generally smooth upper surface, smoothly transitioning to a generally smooth side surface without asperities.

46. (Original) The planarizing pad of claim 45 wherein the texture elements have a plurality of abrasive particles embedded therein.

47. (Original) The planarizing pad of claim 45 wherein the texture elements include partially spherical droplets.

48. (Original) The planarizing pad of claim 45 wherein the texture elements have a cross-sectional dimension of from approximately 50 microns to approximately 200 microns.

49. (Original) The apparatus of claim 45 wherein the texture elements project from the support portion by a distance of from about 10 microns to about 200 microns.

50. (Original) The planarizing pad of claim 45 wherein the support portion is elongated in a longitudinal direction.

51. (Original) The planarizing pad of claim 45 wherein the support portion has a generally circular planform shape.

52. (Original) The planarizing pad of claim 45 wherein the support portion includes a support material, further comprising an adhesive material between the support material and the texture elements.

53. (Original) The planarizing pad of claim 45, further comprising a selected chemical agent embedded in the texture elements.

54. (Original) The planarizing pad of claim 53 wherein the selected chemical agent includes a surfactant or an oxidizer.

55. (Original) The planarizing pad claim 45 wherein the texture elements have a first spacing in a first region of the support portion and a second spacing in a second region of the support material with the first spacing different than the second spacing.

56. (Original) The planarizing pad of claim 45 wherein the texture elements and the support portion have the same chemical composition.

57. (Original) A planarizing pad for planarizing a microelectronic substrate, comprising:

a support portion; and

a plurality of discrete texture elements disposed on the support portion, the texture elements being initially separate from the support portion and subsequently bonded to the support portion with portions of the texture elements being spaced apart from each other and projecting from the support portion, each texture element having a generally smooth upper surface.

58. (Original) The planarizing pad of claim 57 wherein the texture elements have a plurality of abrasive particles embedded therein.

59. (Original) The planarizing pad of claim 57 wherein the texture elements include partially spherical droplets.

60. (Original) The planarizing pad of claim 57 wherein the texture elements have a cross-sectional dimension of from approximately 50 microns to approximately 200 microns.

61. (Original) The planarizing pad of claim 57 wherein the texture elements project from the surface of the support material by a distance of from about 10 microns to about 200 microns.

62. (Original) The planarizing pad of claim 57 wherein the support portion includes a support material, further comprising an adhesive material between the support material and the texture elements.

63. (Original) The planarizing pad of claim 57, further comprising a selected chemical agent embedded in the texture elements.

64. (Original) The planarizing pad of claim 57 wherein the texture elements have a first spacing in a first region of the support portion and a second spacing in a second region of the support portion with the first spacing different than the second spacing.

65. (Original) The planarizing pad of claim 57 wherein the texture elements and the support portion have the same chemical composition.

66-72. (Canceled)